

**MATERIAL**  
 INSULATOR: GLASS-REINFORCED THERMOPLASTIC PPS.  
 CONTACT: COPPER ALLOY.  
 PLATING: MATING AREA - SELECTED GLOD OVER NICKEL.  
 SOLDER AREA - TIN OVER NICKEL.

**ELECTRICAL**  
 VOLTAGE RATING: 250 VAC RMS.  
 CURRENT RATING: 1 AMP.  
 DIELECTRICAL WITHSTANDING VOLTAGE: 500 VAC RMS 60 Hz FOR 1 MINUTE.  
 INSULATION RESISTANCE: 1000 MEGOHMS MIN AT 500 VDC.  
 CONTACT RESISTANCE: 30 MILLIOHMS MAX AT 1 AMP DC.

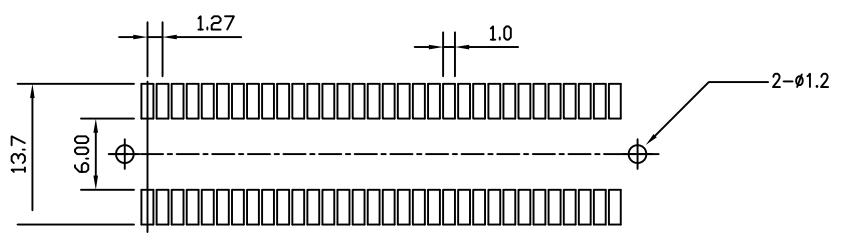
**MECHANICAL**  
 RETENTION FORCE: 460 GRAMS MIN PER CONTACT.  
 INSERTION FORCE: 230 GRAMS MAX PER CONTACT PER.  
 WITHDRAWAL FORCE: 15 GRAMS MIN PER CONTACT PER.

**ENVIRONMENTAL**  
 TEMPERATURE RANGE: -55°C TO +85°C.

HEL-V81P-xxx-LF  
 LEADFREE

RoHS Compliant

SECTION A-A



RECOMMENDED PCB LAYOUT (TOP VIEW)

| Pin NO. \ DIM. | A     | B     | C     | D     |
|----------------|-------|-------|-------|-------|
| 20PIN          | 16.26 | 13.97 | 11.43 | 15.09 |
| 30PIN          | 22.60 | 20.32 | 17.78 | 21.44 |

**MORETHANALL**  
 CONNECTORS  
 ASSEMBLIES

煜倫股份有限公司

|                       |           |               |  |  |
|-----------------------|-----------|---------------|--|--|
| PART NO. HEL-V81P-xxx |           | CHECKED BY CY | TOLERANCES ARE<br>.X ± 0.2<br>.XX ±<br>.XXX ±<br>AWG | DESCRIPTION:<br>1.27 CARD EDGE SMT , POST TYPE LOW PROFILE |
| DWG NO. HEL-V81P-xxx  |           |               |  |  |
| FILE NO.              |           | DRAWING BY    | AREA   | REVISIONS  |
| UNIT / mm             | SCALE 1:1 | PROJECTION    |  |  |